

PRODUCT NUMBER
91269-XXXXLF

PLATING
0 = 0.20 μ m GOLD/GXT ON CONTACT AREA
2.0 μ m MIN MATTE TIN ON TAILS
1 = 0.76 μ m GOLD/GXT ON CONTACT AREA
2.0 μ m MIN MATTE TIN ON TAILS
3 = 0.38 μ m GOLD/GXT ON CONTACT AREA
2.0 μ m MIN MATTE TIN ON TAILS
UNDERPLATING 1.27 μ m Ni MIN

T = FULL MATTE TIN 2 μ m-5 μ m
1.27 μ m Ni MIN UNDERPLATING

NOTES:

1 - HOUSING MTRL : HIGH TEMPERATURE
THERMOPLASTIC. UL94V-0 COLOR: CREAM

2 - PIN MATERIAL : COPPER ALLOY

3 - PACKAGING
TR = TAPE & REEL (SEE TAB45 FOR PRODUCT AVAILABILITY)

4 - 7IN MIN RETENTION IN EITHER DIRECTION

5 - TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS

EXAMPLE : 8 POS N x 2.0 = 16.0mm

6 - ROHS COMPATIBLE PRODUCT SPECIFICATIONS

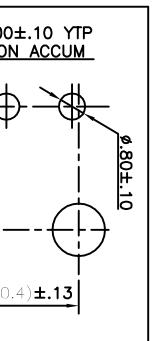
a - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.

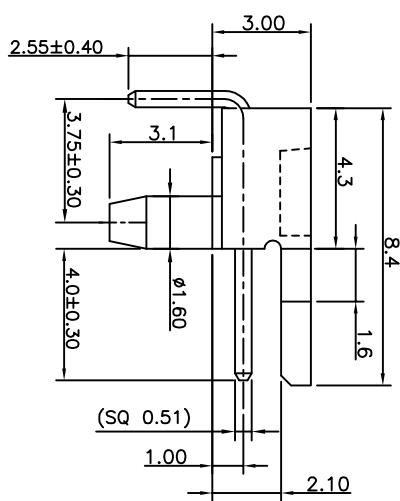
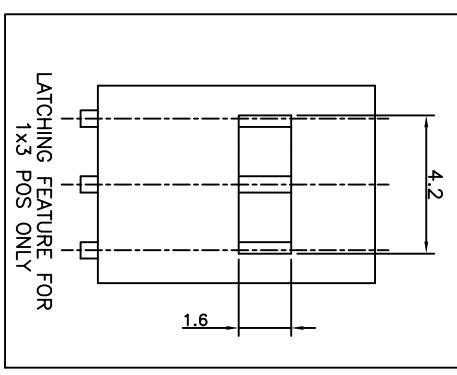
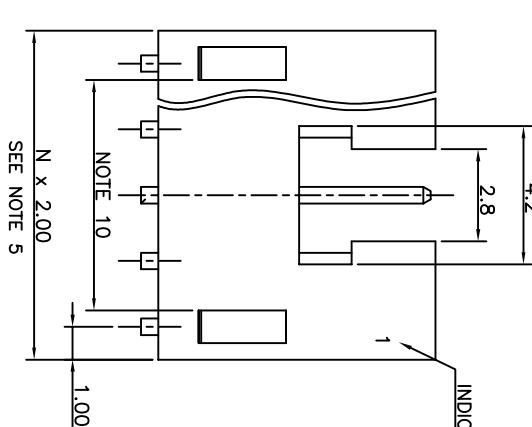
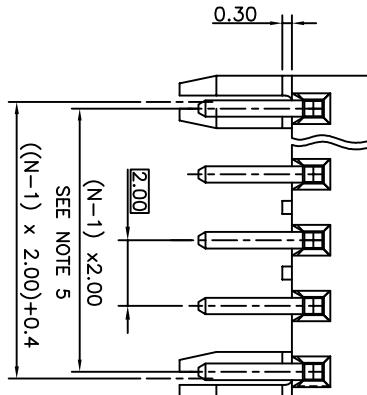
b - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920

c - THIS PRODUCT MEETS EUROPEAN DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DISCUSSED
IN GS-47-0004



RECOMMENDED HOLE PATTERN
SEE NOTE 6



C

B

A

C

mat'l. code SEE TABLE	surface ISO 1302	tolerance ISO 406	projection 101	product family MINITEK
ltr. ecn no L B-16822 JCO	dr. date 14.01.23	tolerances unless otherwise specified X ±0.3	title MINITEK, TMT, SR	
M B-19186 LMU	14.10.24	angles XX ±0.13	RA, POL & LATCHING	
G F05-0128 LMU	05.02.21	linear XXX ±0.05	scale 5:1	
H F06-0210 LMU	06.07.04	depth mm		
J F08-0145 EEA	17.04.08	depth mm		
K B-16048 JCO	13.10.14	depth mm		
sheet revision sheet index				